May 24, 2016

Invensas to Showcase 3D Packaging, Interconnect and Bonding Solutions at IEEE Electronic Components and Technology Conference

SAN JOSE, Calif.--(BUSINESS WIRE)-- Tessera Technologies, Inc. (Nasdaq: TSRA), announced today that its wholly owned subsidiary Invensas Corporation will showcase its advanced semiconductor packaging and interconnect solutions at the upcoming IEEE Electronic Components and Technology Conference, taking place May 31-June 3 in Las Vegas, Nevada.

What: IEEE Electronic Components Technology Conference
Date: May 31-June 3, 2016
Location: The Cosmopolitan of Las Vegas, Las Vegas, Nevada
Booth Number: 101
Registration Information: Conference attendees can register for the show at http://ectc.net/.
Details: At the show, Invensas will showcase its Bond-Via-Array™ (BVA®) fine pitch vertical interconnect technology for Package-on-Package (PoP) and System-in-Package (SiP) applications plus ZiBond® homogeneous direct bond and Direct Bond Interconnect (DBI®) hybrid bonding technologies for wafer and die level 3D interconnect applications.

BVA is a fine pitch vertical interconnect technology that forms package level 3D interconnects between active or passive devices utilizing the existing wire bond infrastructure. This technology provides the industry with unmatched tolerance to process variations, which translates into improved yield and cost efficiencies. ZiBond is a low temperature homogenous (oxide-to-oxide) direct bonding technology that forms strong bonds between wafers or die with same or different coefficients of thermal expansion (CTE), without the need for the application of external pressure. DBI is a low temperature hybrid direct bonding technology that allows wafers or die to be bonded with exceptionally fine pitch 3D electrical interconnect at low cost-of-ownership.

For more information about BVA, ZiBond and DBI technologies, visit www.invensas.com.

About Tessera Technologies, Inc.

Tessera Technologies, Inc., including its Invensas and FotoNation subsidiaries, licenses technologies and intellectual property to customers for use in areas such as mobile computing and communications, memory and data storage, and 3D-IC technologies, among others. Our technologies include semiconductor packaging and interconnect solutions, and computational imaging and computer vision products and solutions for mobile and other vision systems. For more information call +1.408.321.6000 or visit www.tessera.com or www.invensas.com.

Tessera, the Tessera logo, Invensas, the Invensas logo, Bond-Via-Array and BVA, are trademarks or registered trademarks of affiliated companies of Tessera Technologies, Inc. in the United States and other countries. All other company, brand and product names may be trademarks or registered trademarks of their respective companies.

Safe Harbor Statement

This press release contains forward-looking statements, which are made pursuant to the safe harbor provisions of the Private Securities Litigation Reform Act of 1995. Forward-looking statements involve risks and uncertainties that could cause actual results to differ significantly from those projected, particularly with respect to the characteristics, benefits, and features of BVA and potential future uses of such technology in future products. Material factors that may cause results to differ from the statements made include the plans or operations relating to the businesses of Tessera Technologies, Inc. (the "Company"); market or industry conditions; changes in patent laws, regulation or enforcement, or other factors that might affect the Company's ability to protect or realize the value of its intellectual property; the expiration of license agreements and the cessation of related royalty income; the failure, inability or refusal of licensees to pay royalties; initiation, delays, setbacks or losses relating to the Company's intellectual property or intellectual property litigations, or invalidation or limitation of key patents; fluctuations in operating results due to the timing of new license agreements and royalties, or due to legal costs; the risk of a decline in demand for semiconductors and products utilizing FotoNation technologies; failure by the industry to use technologies covered by the Company's patents; the expiration of the Company's patents; the Company's ability to successfully complete and integrate acquisitions of businesses; the risk of loss of, or decreases in production orders from, customers of acquired businesses; financial and regulatory risks associated with the international nature of the Company's businesses; failure of the Company's products to achieve technological feasibility or profitability; failure to successfully commercialize the Company's products; changes in demand for the products of the Company's customers; limited opportunities to license technologies due to high

concentration in the markets for semiconductors and related products and smartphone imaging; and the impact of competing technologies on the demand for the Company's technologies. You are cautioned not to place undue reliance on the forward-looking statements, which speak only as of the date of this release. The Company's filings with the Securities and Exchange Commission, including its Annual Report on Form 10-K for the year ended Dec. 31, 2015 and its Quarterly Report on Form 10-Q for the quarter ended Mar. 31, 2016, include more information about factors that could affect the Company's financial results. The Company assumes no obligation to update information contained in this press release. Although this release may remain available on the Company's website or elsewhere, its continued availability does not indicate that the Company is reaffirming or confirming any of the information contained herein.

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